

1.5A, 200V - 1000V Surface Mount Rectifiers

FEATURES

- Ideal for automated placement
- · Compact package size
- High surge current capability
- Low power loss, high efficiency
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition

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- High frequency rectification
- Freewheeling application
- Switching mode converters and inverters in computer, automotive and telecommunication.

MECHANICAL DATA

- Case: SOD-123W
- Molding compound meets UL 94V-0 flammability rating
- Moisture sensitivity level: level 1, per J-STD-020
- Part no. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- · Polarity: Indicated by cathode band
- Weight: 19mg (approximately)

KEY PARAMETERS							
PARAMETER	VALUE	UNIT					
$I_{F(AV)}$	1.5	Α					
V_{RRM}	200 - 1000	V					
I _{FSM}	50	Α					
$T_{\text{J MAX}}$	175	°C					
Package	SOD-123W						
Configuration	Single die						





SOD-123W

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)							
DADAMETED	CVMDOL	S15	S15	S15	S15	S15	HALLT
PARAMETER SYMBOI		DLW	GLW	JLW	KLW	MLW	UNIT
Marking and on the daying		15	15	15	15	15	
Marking code on the device		DLW	GLW	JLW	KLW	MLW	
Repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Forward current	I _{F(AV)}			1.5			Α
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I _{FSM}			50			Α
Junction temperature	T_J		-55 to +175				°C
Storage temperature	T _{STG}		-5	55 to +17	75		°C



THERMAL PERFORMANCE							
PARAMETER	SYMBOL	LIMIT	UNIT				
Junction-to-lead thermal resistance	$R_{\Theta JL}$	29	°C/W				
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	85	°C/W				
Junction-to-case thermal resistance	$R_{\Theta JC}$	31	°C/W				

Thermal Performance Note: Units mounted on recommended PCB (5mm*5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)							
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT		
	I _F = 1A, T _J = 25°C		0.94	1.05	V		
Forward voltage per diode (1)	I _F = 1.5A, T _J = 25°C	V _F	0.98	1.1	V		
	I _F = 1A, T _J = 125°C		0.81	1	V		
	I _F = 1.5A, T _J = 125°C		0.87	1.05	V		
Deverse everent @ reted // nor diade (2)	T _J = 25°C	1	0.06	1	μΑ		
Reverse current @ rated V _R per diode ⁽²⁾	T _J = 125°C	I _R	6.06	100	μΑ		
Junction Capacitance	1 MHz, V _R =4.0V	CJ	10	-	ρF		

Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

ORDERING INFORMATION							
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING		
S15xLW		RV	0	SOD-123W	3,000 / 7" Reel		
(Note 1,2)	Н	RQ	G	SOD-123W	10,000 / 13" Reel		

Notes:

- 1. "x" defines voltage from 200V (S15DLW) to 1000V (S15MLW)
- 2. Whole series with green compound (halogen-free)

EXAMPLE P/N							
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION		
S15MLWHRVG	S15MLW	Н	RV	G	AEC-Q101 qualified Green compound		



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

2 AVERAGE FORWARD CURRENT (A) 1.5 1 0.5 Resistive or inductive load with heat sink 0 30 60 90 120 150 CASE TEMPERATURE (°C)

Fig.2 Typical Junction Capacitance

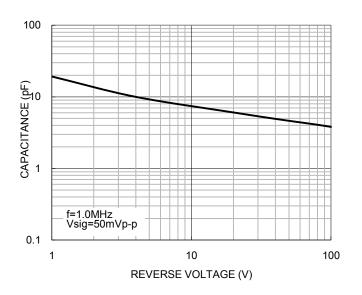


Fig.3 Typical Reverse Characteristics

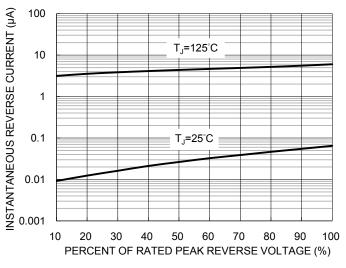
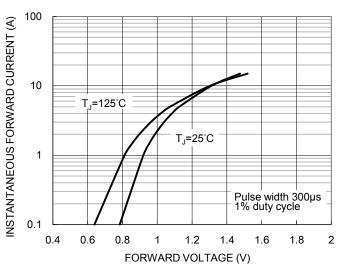


Fig.4 Typical Forward Characteristics

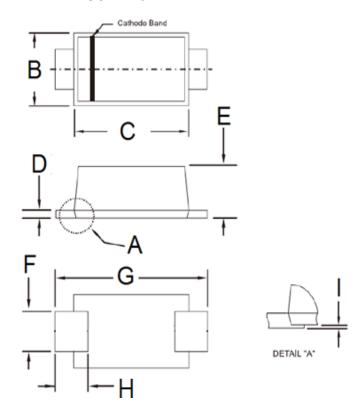


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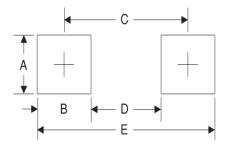
PACKAGE OUTLINE DIMENSIONS

SOD-123W



DIM.	Unit	(mm)	Unit (inch)		
DIIVI.	Min	Max	Min	Max	
В	1.70	1.90	0.067	0.075	
С	2.60	2.90	0.102	0.114	
D	0.10	0.22	0.004	0.009	
Е	0.90	1.02	0.035	0.040	
F	0.90	1.05	0.035	0.041	
G	3.60	3.80	0.142	0.150	
Н	0.50	0.85	0.020	0.033	
Ī	0.00	0.10	0.000	0.004	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	1.4	0.055
В	1.2	0.047
С	3.1	0.122
D	1.9	0.075
Е	4.3	0.169

MARKING DIAGRAM



P/N = Marking Code G = Green Compound

YW = Date Code F = Factory Code



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